INTEGRATED CIRCUITS

DATA SHEET

74LVC652

Octal transceiver/register with dual enable (3-State)

Product specification
Supercedes data of 1993 Dec 01
IC24 Data Handbook





Octal transceiver/register with dual enable (3-State)

74LVC652

*FEATURES

- Wide supply voltage range of 1.2V to 3.6V
- In accordance with JEDEC standard no. 8-1A
- CMOS low power consumption
- Direct interface with TTL levels
- 5 Volt tolerant inputs/outputs, for interfacing with 5 Volt logic

DESCRIPTION

The 74LVC652 is a high performance, low-power, low-voltage Si-gate CMOS device, superior to most advanced CMOS compatible TTL families.

Inputs can be driven from either 3.3V or 5.0V devices. In 3-State operation, outputs can handle 5V. This feature allows the use of these devices as translators in a mixed 3.3V/5V environment.

The 74LVC652 consist of 8 non-inverting bus transceiver circuits with 3-State outputs, D-type flip-flops and control circuitry arranged for multiplexed transmission of data directly from the internal registers. Data on the 'A' or 'B' or both buses, will be stored in the internal registers, at the appropriate clock inputs (CPAB or CPBA) regardless of the select inputs (SAB and SBA) or output enable (OEAB and OEBA) control inputs. Depending on the select inputs SAB and SBA data can directly go from input to output (real time mode) or data can be controlled by the clock (storage mode), this is when the OEn inputs this operating mode permits. The output enable inputs OEAB and OEBA determine the operation mode of the transceiver.

When OEAB is LOW, no data transmission from An to Bn is possible and when $\overline{\text{OE}}\text{BA}$ is HIGH, there is no data transmission from Bn to An possible. When SAB and SBA are in the real time transfer mode, it is also possible to store data without using the internal D-type flip-flops by simultaneously enabling OEAB and OEBA. In this configuration each output reinforces its input.

QUICK REFERENCE DATA

GND = 0V; $T_{amb} = 25^{\circ}C$; $t_r = t_f \le 2.5 \text{ ns}$

SYMBOL	PARAMETER	CONDITIONS	TYPICAL	UNIT
t _{PHL} /t _{PLH}	Propagation delay A _n to B _n ; B _n to A _n	$C_L = 50pF$ $V_{CC} = 3.3V$	5.0	ns
f _{max}	Maximum clock frequency	1	150	MHz
C _I	Input capacitance		5.0	pF
C _{PD}	Power dissipation capacitance per latch	Notes 1, 2	45	pF

NOTES:

- 1. C_{PD} is used to determine the dynamic power dissipation (P_D in μW)

 - $P_D = C_{PD} \times V_{CC}^2 \times f_i + \Sigma (C_L \times V_{CC}^2 \times f_o)$ where: f_i = input frequency in MHz; C_L = output load capacitance in pF; f_o = output frequency in MHz; V_{CC} = supply voltage in V;

 - $\Sigma (C_L \times V_{CC}^2 \times f_0) = \text{sum of the outputs.}$
- 2. The condition is $V_I = GND$ to V_{CC} .

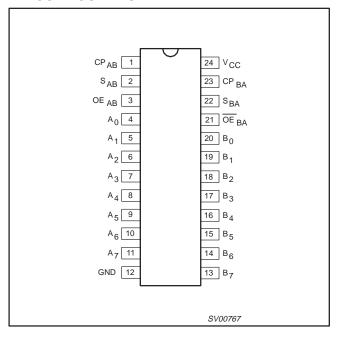
ORDERING AND PACKAGE INFORMATION

PACKAGES	TEMPERATURE RANGE	OUTSIDE NORTH AMERICA	NORTH AMERICA	PKG. DWG. #
24-Pin Plastic SO	–40°C to +85°C	74LVC652 D	74LVC652 D	SOT137-1
24-Pin Plastic SSOP Type II	-40°C to +85°C	74LVC652 DB	74LVC652 DB	SOT340-1
24-Pin Plastic TSSOP Type I	-40°C to +85°C	74LVC652 PW	4LVC652PW DH	SOT355-1

Octal transceiver/register with dual enable (3-State)

74LVC652

PIN CONFIGURATION



PIN DESCRIPTION

PIN NUMBER	SYMBOL	FUNCTION
1	CP _{AB}	'A' to 'B' clock input (LOW-to-HIGH, edge-triggered)
2	S _{AB}	Select 'A' to 'B' source input
3	OE _{AB}	Output enable B to A input (active LOW)
4, 5, 6, 7, 8, 9, 10, 11	A ₀ to A ₇	'A' data inputs/outputs
12	GND	Ground (0V)
20, 19, 18, 17, 16, 15, 14, 13	B ₀ to B ₇	'B' data inputs/outputs
21	OE BA	Output enable A to B input
22	S _{BA}	Select 'B' to 'A' source input
23	CP _{BA}	'B' to 'A' clock input (LOW-to-HIGH, edge-triggered)
24	V _{CC}	Positive supply voltage

FUNCTION TABLE

INPUTS						DATA	\ I/O *	FUNCTION
OE _{AB}	OE _{BA}	CP _{AB}	CP _{BA}	S _{AB}	S _{BA}	A ₀ to A ₇	B ₀ to B ₇	FUNCTION
L L	H H	H or L ↑	H or L ↑	X X	X X	input	input	isolation store A and B data
X H	H H	↑	H or L ↑	X L	X X	input input	un * output	store A, hold B, store A in both registers
L L	X L	H or L ↑	↑	X X	X L	un * output	input input	hold A, store B, store B in both registers
L L	L L	X	X H or L	X X	L H	output	input	real-time B data to A bus stored B data to A bus
H H	H H	X H or L	X X	L H	X X	input	output	real-time A data to B bus stored A data to B bus
Н	L	H or L	H or L	Н	Н	output	output	stored A data to B bus and stored B data to A bus

The data output functions may be enabled or disabled by various signals at the OE_{AB} and OE_{BA} inputs. Data input functions are always enabled, i.e., data at the bus inputs will be stored on every LOW-to-HIGH transition on the clock inputs.

= unspecified = HIGH voltage level un Н

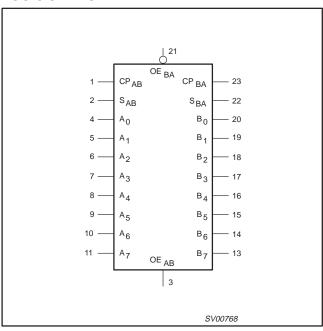
L X ↑ = LOW voltage level = Don't care

= LOW-to-HIGH level transition

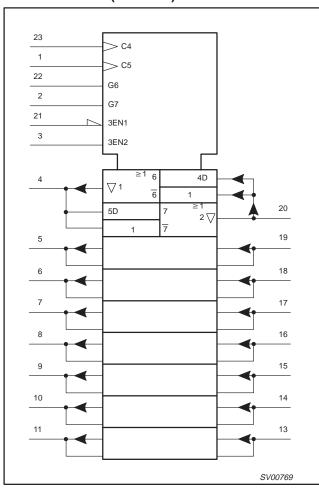
Octal transceiver/register with dual enable (3-State)

74LVC652

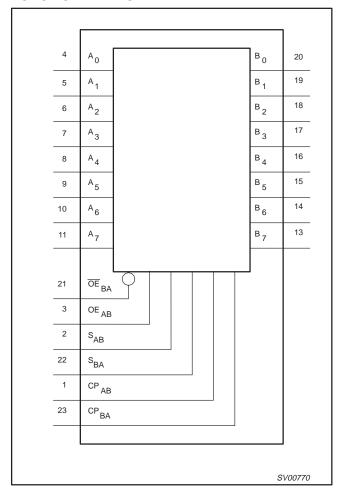
LOGIC SYMBOL



LOGIC SYMBOL (IEEE/IEC)



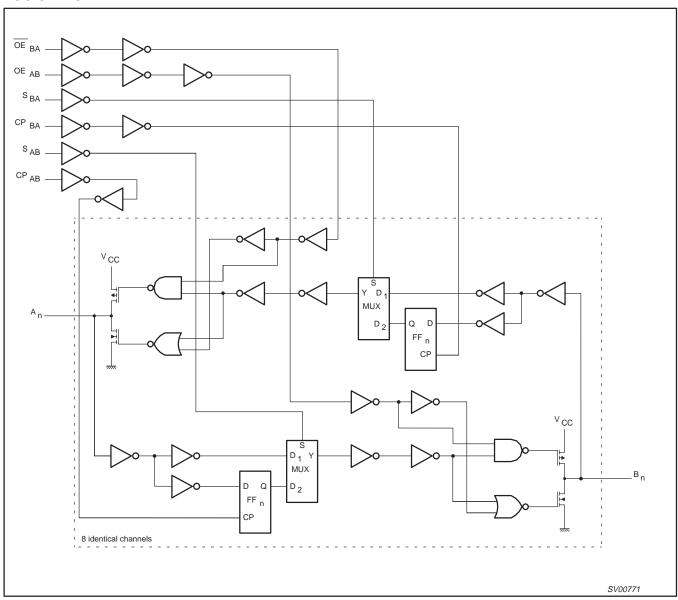
FUNCTIONAL DIAGRAM



Octal transceiver/register with dual enable (3-State)

74LVC652

LOGIC DIAGRAM



Octal transceiver/register with dual enable (3-State)

74LVC652

RECOMMENDED OPERATING CONDITIONS

SYMBOL	PARAMETER	CONDITIONS	LIM	ITS	UNIT
STWIBOL	FARAMETER	WETER GORDING		MAX	UNIT
V _{CC}	DC supply voltage (for max. speed performance)		2.7	3.6	V
\ vcc	DC supply voltage (for low-voltage applications)		1.2	3.6	V
V _I	DC input voltage range		0	5.5	V
V _{I/O}	DC input voltage range for I/Os		0	V _{CC}	V
Vo	DC output voltage range		0	V _{CC}	V
T _{amb}	Operating free-air temperature range		-40	+85	°C
t _r , t _f	Input rise and fall times	$V_{CC} = 1.2 \text{ to } 2.7V$ $V_{CC} = 2.7 \text{ to } 3.6V$	0	20 10	ns/V

ABSOLUTE MAXIMUM RATINGS¹

In accordance with the Absolute Maximum Rating System (IEC 134) Voltages are referenced to GND (ground = 0V)

SYMBOL	PARAMETER	CONDITIONS	RATING	UNIT
V _{CC}	DC supply voltage		-0.5 to +4.6	V
I _{IK}	DC input diode current	V ₁ < 0	- 50	mA
VI	DC input voltage	Note 2	−0.5 to +5.5	V
I _{OK}	DC output diode current	$V_{O} > V_{CC}$ or $V_{O} < 0$	±50	mA
V	DC output voltage; output HIGH or LOW	Note 2	-0.5 to V _{CC} +0.5	V
V _{I/O}	DC input voltage; output 3-State	Note 2	-0.5 to V _{CC} +0.5	V
I _O	DC output diode current	$V_{O} = 0$ to V_{CC}	±50	mA
I _{GND} , I _{CC}	DC V _{CC} or GND current		±100	mA
T _{stg}	Storage temperature range		-65 to +150	°C
Ртот	Power dissipation per package – plastic mini-pack (SO) – plastic shrink mini-pack (SSOP and TSSOP)	above +70°C derate linearly with 8 mW/K above +60°C derate linearly with 5.5 mW/K	500 500	mW

NOTES

Stresses beyond those listed may cause permanent damage to the device. These are stress ratings only and functional operation of the
device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to
absolute-maximum-rated conditions for extended periods may affect device reliability.

^{2.} The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

Octal transceiver/register with dual enable (3-State)

74LVC652

DC ELECTRICAL CHARACTERISTICS

Over recommended operating conditions voltages are referenced to GND (ground = 0V)

				L	UNIT		
SYMBOL	PARAMETER	TEST CONDITION	NS	Temp = -40°C to +85°C			
				MIN	TYP ¹	MAX	
V	LHCL Lovel Input veltage	V _{CC} = 1.2V		V _{CC}			V
V _{IH}	HIGH level Input voltage	V _{CC} = 2.7 to 3.6V		2.0			V
V.	LOW level lanut voltage	V _{CC} = 1.2V				GND	V
V _{IL}	LOW level Input voltage	V _{CC} = 2.7 to 3.6V				0.8	V
		$V_{CC} = 2.7V$; $V_I = V_{IH}$ or V_{IL} ; $I_O =$	= –12mA	V _{CC} - 0.5			
V	HICH level output voltage	$V_{CC} = 3.0V$; $V_I = V_{IH}$ or V_{IL} ; $I_O = -100\mu A$		V _{CC} -0.2	V _{CC}		\ \ \
V _{OH}	HIGH level output voltage	$V_{CC} = 3.0V$; $V_I = V_{IH}$ or V_{IL} ; $I_O = -18$ mA		V _{CC} -0.6			
		$V_{CC} = 3.0V$; $V_I = V_{IH}$ or V_{IL} ; $I_O =$: –24mA	V _{CC} -0.8			
		$V_{CC} = 2.7V$; $V_I = V_{IH}$ or V_{IL} ; $I_O =$	= 12mA			0.40	
V _{OL}	LOW level output voltage	$V_{CC} = 3.0V$; $V_I = V_{IH}$ or V_{IL} ; I_O	= 100μΑ		GND	0.20	V
		$V_{CC} = 3.0V$; $V_I = V_{IH}$ or V_{IL} ; $I_O =$: 24mA			0.55	
I _I	Input leakage current	$V_{CC} = 3.6V; V_I = 5.5V \text{ or GND}$	Not for I/O pins		± 0.1	±5	μΑ
I _{IHZ} /I _{ILZ}	Input current for common I/O pins	$V_{CC} = 3.6V; V_I = 5.5V \text{ or GND}$			±0.1	±15	μΑ
l _{OZ}	3-State output OFF-state current	$V_{CC} = 3.6V$; $V_I = V_{IH}$ or V_{IL} ; V_O	= 5.5V or GND		0.1	±10	μΑ
I _{OFF}	Power off leakage current	$V_{CC} = 0.0V; V_I = 5.5V; V_O = 5.5$	5V		0.1	±10	μА
I _{CC}	Quiescent supply current	$V_{CC} = 3.6V$; $V_I = V_{CC}$ or GND; I	O = 0		0.1	10	μΑ
Δl _{CC}	Additional quiescent supply current per input pin	$V_{CC} = 2.7V \text{ to } 3.6V; V_I = V_{CC} - 0.000$	0.6V; I _O = 0		5	500	μА

NOTES:

^{1.} All typical values are at V_{CC} = 3.3V and T_{amb} = 25°C.

Octal transceiver/register with dual enable (3-State)

74LVC652

AC CHARACTERISTICS

GND = 0 V; $t_r = t_f \leq 2.5 \text{ ns}$; $C_L = 50 \text{ pF}$

			LIMITS							
SYMBOL	PARAMETER	WAVEFORM	NAVEFORM $V_{CC} = 3.3V \pm 0.3V$		V _{CC} =	= 2.7V	V _{CC} = 1.2V		UNIT	
			MIN	TYP ¹	MAX	MIN	MAX	MIN	TYP	
t _{PHL} /t _{PLH}	Propagation delay An to Bn, Bn to An	Figures 1, 5	1.5	4.6	7.9	1.5	9.2	1.5	24	ns
t _{PHL} /t _{PLH}	Propagation delay CP_{AB} , CP_{BA} to B_n , A_n	Figures 2, 5	1.5	5.2	8.9	1.5	11	1.5	26	ns
t _{PHL} /t _{PLH}	Propagation delay S_{AB} , S_{BA} to B_n , A_n	Figures 3, 5	1.5	5.2	8.8	1.5	11	1.5	27	ns
t _{PZH} /t _{PZL}	3-State output enable time OE _{AB} to Bn	Figures 4, 5	1.5	4.8	8.0	1.5	10	1.5	20	ns
t _{PHZ} /t _{PLZ}	3-State output disable time OE _{AB} to Bn	Figures 4, 5	1.5	4.4	8.0	1.5	10	1.5	10	ns
t _{PZH} /t _{PZL}	3-State output enable time OE _{BA} to An	Figures 4, 5	1.5	4.8	8.0	1.5	10	1.5	20	ns
t _{PHZ} /t _{PLZ}	3-State output disable time OE _{BA} to An	Figures 4, 5	1.5	4.4	8.0	1.5	10	1.5	10	ns
t _W	Clock pulse width HIGH or LOW CP _{AB} or CP _{BA}	Figures 4, 5	-	3.0	-	3.0	_	-	-	ns
t _{su}	Set-up time An, Bn to CP _{AB} , CP _{BA}	Figure 2	1.5	0.5	_	1.5	_	-	_	ns
t _h	Hold time An, Bn to CP _{AB} , CP _{BA}	Figure 2	1.0	0	ı	1.0	_	-	_	ns
f _{max}	Maximum clock pulse frequency	Figure 2	7.5	150	_	-	_	_	_	MHz

NOTE:

AC WAVEFORMS

 V_{M} = 1.5V at $V_{CC}\,\geq\,2.7V$

 V_{M} = 0.5V * V_{CC} at V_{CC} < 2.7V

 $\ensuremath{V_{OL}}$ and $\ensuremath{V_{OH}}$ are the typical output voltage drop that occur with the output load.

 $V_X = V_{OL} + 0.3V$ at $V_{CC} \ge 2.7V$ $V_X = V_{OL} + 0.1V_{CC}$ at $V_{CC} < 2.7V$

 $V_Y = V_{OH} - 0.3V$ at $V_{CC} \ge 2.7V$ $V_Y = V_{OH} - 0.1V_{CC}$ at $V_{CC} < 2.7V$

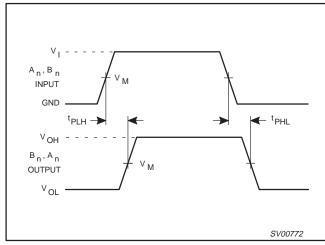


Figure 1. Input An, Bn to output Bn, An propagation delays.

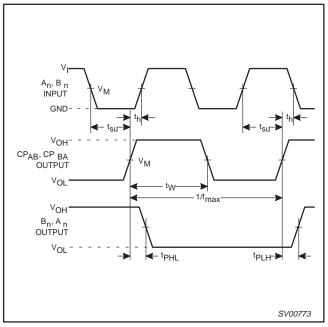


Figure 2. $\,A_n,\,B_n$ to $CP_{AB},\,CP_{BA}$ set-up and hold times, clock CP_{AB}, CP_{BA} pulse width, maximum clock pulse frequency and the CP_{AB} , CP_{BA} to output B_n , A_n propagation delays.

^{1.} These typical values are at V_{CC} = 3.3V and T_{amb} = 25°C.

Octal transceiver/register with dual enable (3-State)

74LVC652

AC WAVEFORMS (Continued)

 V_M = 1.5V at $V_{CC} \ge 2.7V$ V_M = 0.5V * V_{CC} at $V_{CC} < 2.7V$

 V_{OL} and V_{OH} are the typical output voltage drop that occur with the output load.

 $V_X = V_{OL} + 0.3V$ at $V_{CC} \ge 2.7V$

 $V_X = V_{OL} + 0.1 V_{CC}$ at $V_{CC} < 2.7 V$

 $V_Y = V_{OH} - 0.3V$ at $V_{CC} \ge 2.7V$

 $V_Y = V_{OH} - 0.1 V_{CC}$ at $V_{CC} < 2.7 V$

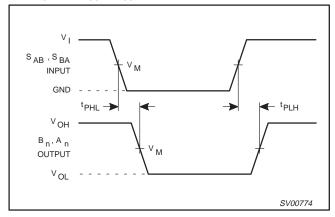


Figure 3. Input S_{AB}, S_{BA} to output B_n, A_n propagation delay times.

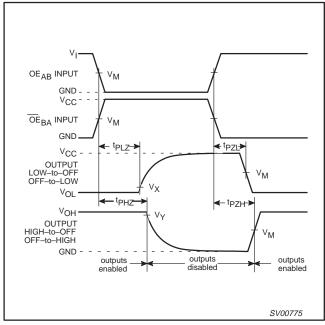


Figure 4. OE inputs (OE $_{AB}$, \overline{OE}_{BA}) to outputs A $_{n}$, B $_{n}$ enable and disable times.

TEST CIRCUIT

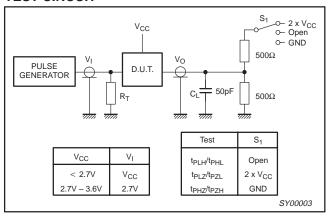


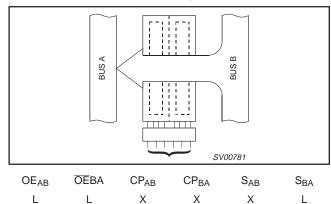
Figure 5. Load circuitry for switching times.

Octal transceiver/register with dual enable (3-State)

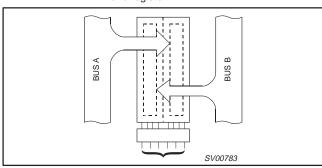
74LVC652

APPLICATION INFORMATION

Real-time transfer; bus B to bus A

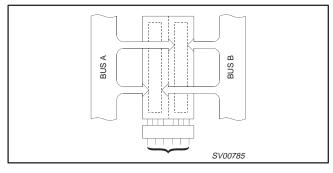


Store A, B or A and B in one register



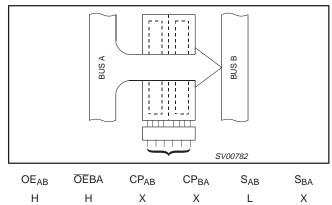
OE_{AB}	OEBA	CPAB	CPBA	S_{AB}	S_{BA}
Χ	Н	\uparrow	\uparrow	L	X
L	X	Χ	\uparrow	Χ	X
1	н	↑	↑	Y	Y

Store bus A in both registers or store bus B in both registers

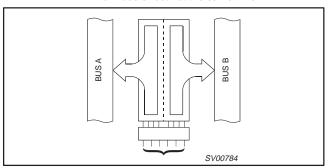


OE_{AB}	OEBA	CPAB	CPBA	S_{AB}	S_{BA}
Н	Н	\uparrow	\uparrow	L	Χ
L	L	\uparrow	\uparrow	X	L

Real-time transfer; bus A to bus B

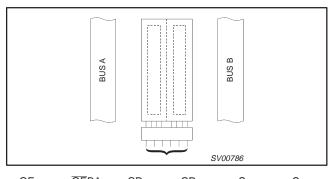


Transfer A stored data to B bus or B stored data to A bus or both at the same time



OE_{AB}	OEBA	CPAB	CPBA	S_{AB}	S_{BA}
Н	Н	H or L	Χ	Н	X
L	L	X	H or L	Χ	Н
Н	L	H or L	H or L	Н	Н

Isolation



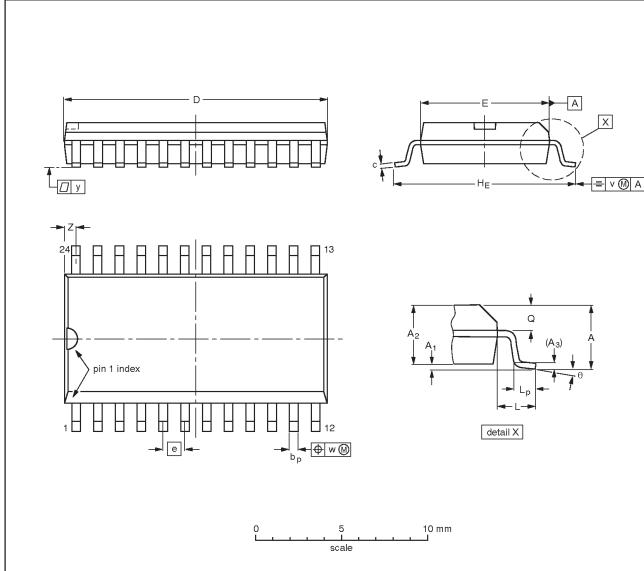
OE_{AB}	OEBA	CPAB	CP _{BA}	S_AB	S_{BA}
L	Н	H or L	H or L	X	X

Octal transceiver/register with dual enable (3-State)

74LVC652

SO24: plastic small outline package; 24 leads; body width 7.5 mm

SOT137-1



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A ₁	A ₂	А3	bр	С	D ⁽¹⁾	E ⁽¹⁾	е	HE	L	Lp	Q	v	w	у	z ⁽¹⁾	θ
mm	2.65	0.30 0.10	2.45 2.25	0.25	0.49 0.36	0.32 0.23	15.6 15.2	7.6 7.4	1.27	10.65 10.00	1.4	1.1 0.4	1.1 1.0	0.25	0.25	0.1	0.9 0.4	8°
inches	0.10	0.012 0.004	0.096 0.089	0.01	0.019 0.014	0.013 0.009	0.61 0.60	0.30 0.29	0.050	0.419 0.394	0.055	0.043 0.016	0.043 0.039	0.01	0.01	0.004	0.035 0.016	0°

Note

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

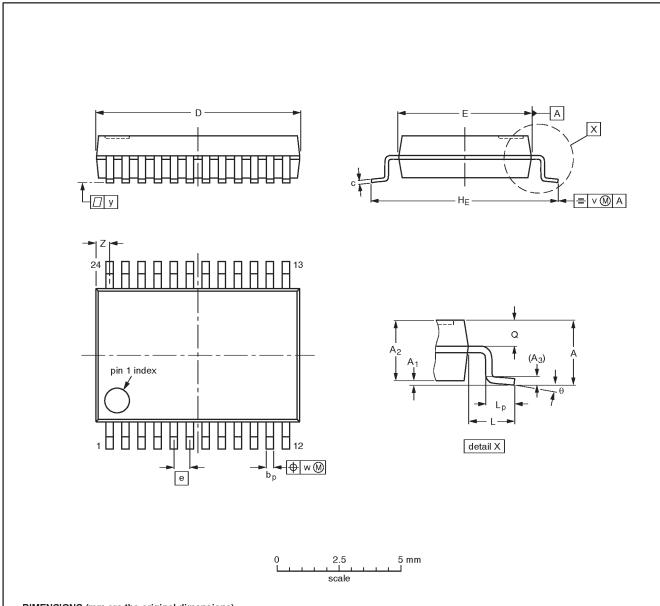
OUTL	INE		REFER	EUROPEAN	ISSUE DATE	
VERS	ION	IEC	JEDEC	EIAJ	PROJECTION	ISSUE DATE
SOT1	37-1	075E05	MS-013AD			-95-01-24 97-05-22

Octal transceiver/register with dual enable (3-State)

74LVC652

SSOP24: plastic shrink small outline package; 24 leads; body width 5.3 mm

SOT340-1



DIMENSIONS (mm are the original dimensions)

UNIT	A max.	Α1	A ₂	A ₃	bр	С	D ⁽¹⁾	E ⁽¹⁾	е	HE	L	Lp	Q	v	w	У	Z ⁽¹⁾	θ
mm	2.0	0.21 0.05	1.80 1.65	0.25	0.38 0.25	0.20 0.09	8.4 8.0	5.4 5.2	0.65	7.9 7.6	1.25	1.03 0.63	0.9 0.7	0.2	0.13	0.1	0.8 0.4	8° 0°

Note

1. Plastic or metal protrusions of 0.20 mm maximum per side are not included.

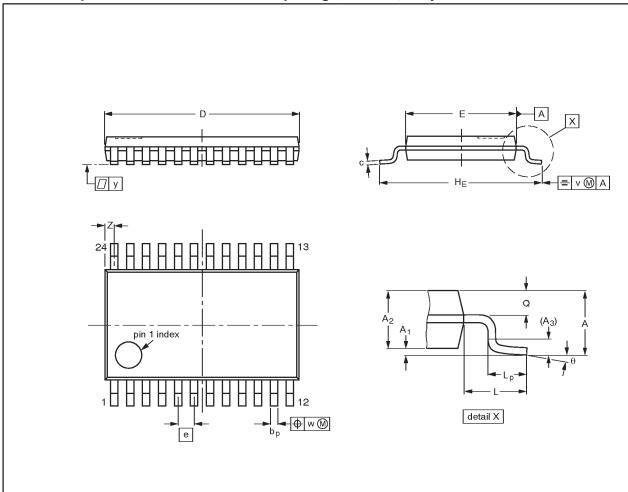
OUTLINE		REFER	RENCES	EUROPEAN	ISSUE DATE	l
VERSION	IEC	JEDEC	EIAJ	PROJECTION	ISSUE DATE	ı
SOT340-1		MO-150AG			93-09-08 95-02-04	

Octal transceiver/register with dual enable (3-State)

74LVC652

TSSOP24: plastic thin shrink small outline package; 24 leads; body width 4.4 mm

SOT355-1





DIMENSIONS (mm are the original dimensions)

UNIT	A max.	Α1	A ₂	A ₃	bр	С	D ⁽¹⁾	E ⁽²⁾	е	HE	L	Lp	Q	v	w	у	Z ⁽¹⁾	θ
mm	1.10	0.15 0.05	0.95 0.80	0.25	0.30 0.19	0.2 0.1	7.9 7.7	4.5 4.3	0.65	6.6 6.2	1.0	0.75 0.50	0.4 0.3	0.2	0.13	0.1	0.5 0.2	8° 0°

Notes

- 1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
- 2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

OUTLINE		REFER	RENCES	EUROPEAN	ISSUE DATE
VERSION	IEC	JEDEC	EIAJ	PROJECTION	ISSUE DATE
SOT355-1		MO-153AD			93-06-16 95-02-04

Octal transceiver/register with dual enable (3-State)

74LVC652

Data sheet status

Data sheet status	Product status	Definition [1]
Objective specification	Development	This data sheet contains the design target or goal specifications for product development. Specification may change in any manner without notice.
Preliminary specification	Qualification	This data sheet contains preliminary data, and supplementary data will be published at a later date. Philips Semiconductors reserves the right to make chages at any time without notice in order to improve design and supply the best possible product.
Product specification	Production	This data sheet contains final specifications. Philips Semiconductors reserves the right to make changes at any time without notice in order to improve design and supply the best possible product.

^[1] Please consult the most recently issued datasheet before initiating or completing a design.

Definitions

Short-form specification — The data in a short-form specification is extracted from a full data sheet with the same type number and title. For detailed information see the relevant data sheet or data handbook.

Limiting values definition — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

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